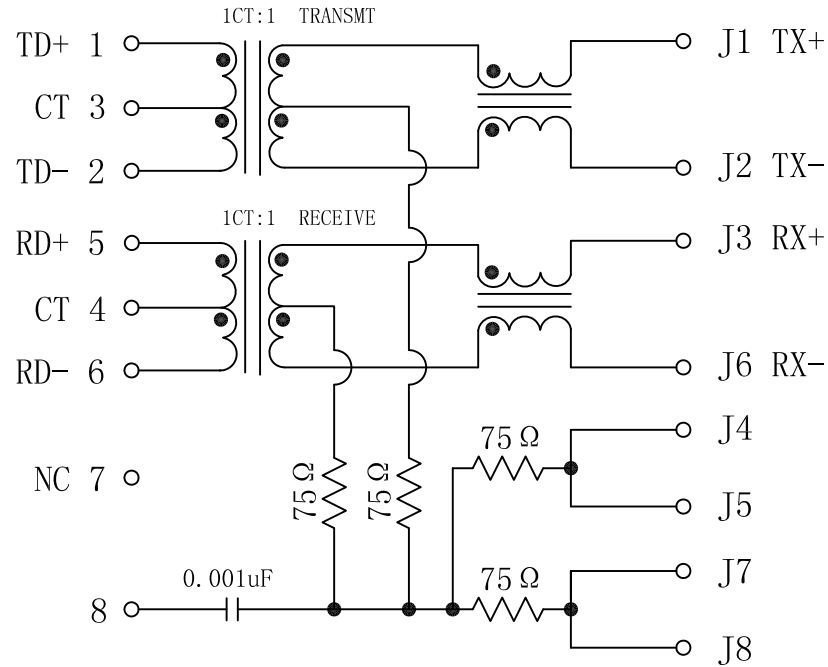


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/16	

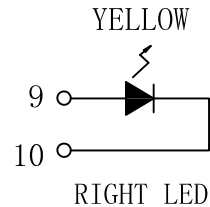
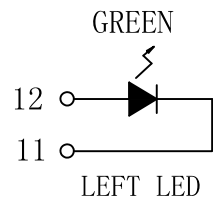
PCB SIDE TO PHY



CABLE

Electrical Specifications @25°C

- Turns Ratio ($\pm 2\%$) :
TX=1CT:1CT RX=1CT:1CT
- OCL: 350uH Min
@100KHz, 100mV, 8mA bias current
- Insertion Loss:
1-65MHz:-1.0dB Max
- Return Loss(dB Min @100 Ω $\pm 15 \Omega$) :
1-10MHz:-20 30MHz:-16
60-80MHz:-12
- Crosstalk(dB Min) :
1-10MHz:-40 30-60MHz:-35
60-100MHz:-30
- Common Mode Rejection(dB Min) :
1-50MHz:-30 50-130MHz:-20
- Isolation Voltage: 1500Vrms Min
- Operating Temperature: 0°C ~ 70°C



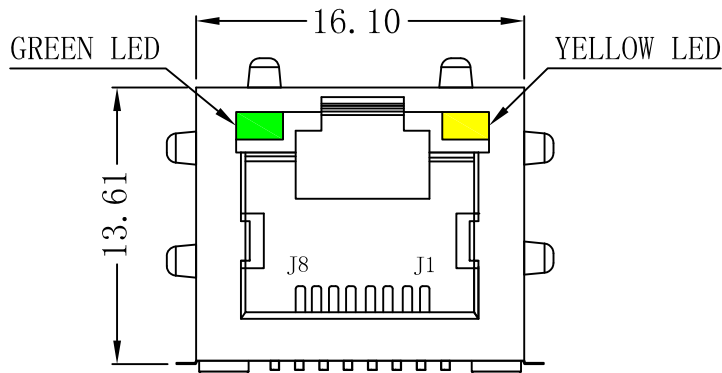
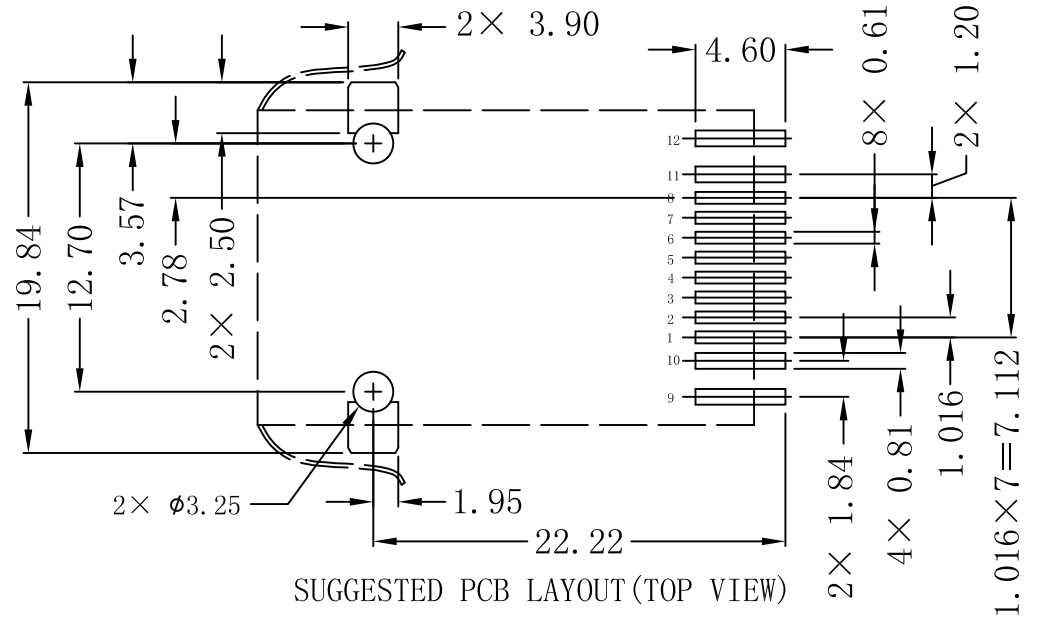
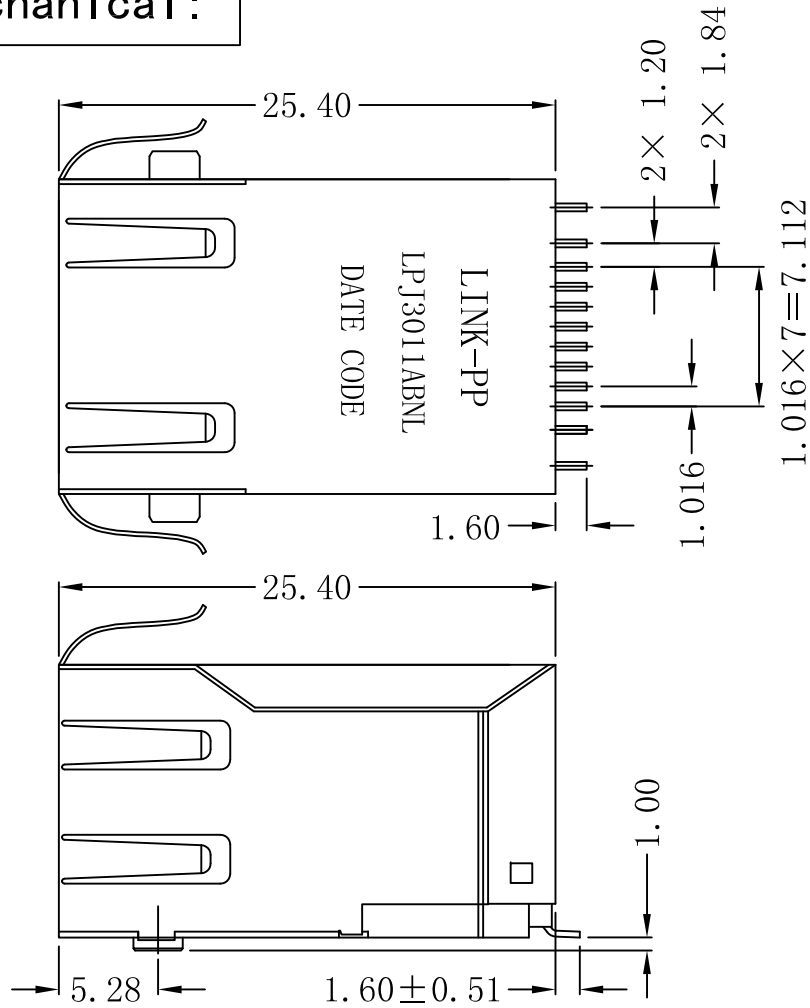
Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
Green	570	1.8~2.6V	10 μ A max
Yellow	585	1.8~2.6V	10 μ A max



X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	± 0.25	CHKD:	
X:XXX	± 0.05	DR: TOM	
ANGLES	$\pm 1^\circ$	UNIT: mm	TITLE: Surface Mount 1x1 Tab-Up Jack With 10/100 Magnetic SMT
			PART NO.: LP3011ABNL
	SCALE: 2/1	SHEET: 1/2	REV: A
			DWG NO.: LP10071605

Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/16	



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic UL94V-0
 Contact/Shield: Copper alloy
 Shield plating: Nickel
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max
 Wave solder tip temperature time: 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: Surface Mount 1x1 Tab-Up Jack With 10/100 Magnetic SMT	
X:XXX	±0.05	DR: TOM	PART NO.: LPJ3011ABNL	
ANGLES	±1°	UNIT: mm	DWG NO.: LP10071605	
SCALE: 2/1		SHEET: 2/2		REV: A